

ABSTRACT OF THE DISCLOSURE

An electronic device connecting method according to a first aspect of the present invention includes: mounting
5 an electronic device having at least one electrode portion on a sheet-like porous member having a hole therein so that the electrode portion is close to the porous member; selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted,
10 with energy lines to form a latent image in an irradiated or non-irradiated portion of the porous member, the predetermined region including a portion close to the electrode portion; after irradiating with the energy lines, filling a conductive material in a hole of the latent image
15 of the porous member to form a conductive portion; and bonding and integrating the porous member, in which the conductive portion is formed, to and with the electronic device.